



Product Change Notification: CBOL-21ZKND337

Date:

30-Jul-2026

Product Category:

8-Bit Microcontrollers

Notification Subject:

CCB 8394 Final Notice: Qualification of MMT as an additional assembly site for ATTINY45-20XU, ATTINY45V-10XUR, ATTINY45-20XUR and ATTINY45V-10XU catalog part numbers (CPN) available in 8L TSSOP (4.4mm) package.

Affected CPNs:

[CBOL-21ZKND337_Affected_CPN_07302026.pdf](#)

[CBOL-21ZKND337_Affected_CPN_07302026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MMT as an additional assembly site for ATTINY45-20XU, ATTINY45V-10XUR, ATTINY45-20XUR and ATTINY45V-10XU catalog part numbers (CPN) available in 8L TSSOP (4.4mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change		Change (Yes/No)
Assembly Site	UTAC Thai Limited (UTL-2) (NSEB)	UTAC Thai Limited (UTL-2) (NSEB)	Microchip Technology Thailand (Branch) (MMT)	Yes

Wire Material	Au	Au	CuPdAu	Yes
Die Attach Material	8200T (PFAS free)	8200T (PFAS free)	8006NS (PFAS free)	Yes
Molding Compound Material	G605L	G605L	G600V	Yes
Lead-Frame Material	C7025	C7025	C7025	No
Lead-Frame Paddle Size	118x104 mils	118x104 mils	118x87 mils	Yes
Lead-Frame Design	See Pre and Post Change Summary attachment for Comparison.			Yes
DAP Surface Prep	Spot Plating	Spot Plating	Bare Cu	Yes

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery and manufacturability by qualifying MMT as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 12 October 2026 (date code: 2642)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	July 2026					>	October 2026				
Work Week	27	28	29	30	31		40	41	42	43	44
Qual Report Availability					X						
Final PCN Issue Date					X						
Estimated Implementation Date									X		

Method to Identify Change: Traceability Code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Note: This is a qualification by similarity (QBS) to CCB#2831 and CCB#6798.

Revision History: July 30, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_CBOL-21ZKND337_Pre_and_Post_Change_Summary.pdf

PCN_CBOL-21ZKND337_Qual_Report_CCB2831.pdf

PCN_CBOL-21ZKND337_Qual_Report_CCB6798.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

ATTINY45-20XU

ATTINY45V-10XUR

ATTINY45-20XUR

ATTINY45V-10XU



Qualification Report Summary

RELIABILITY LABORATORY

PCN #: CBOL-21ZKND337

Date: May 5, 2017

Qualification of MMT as an additional assembly site for ATTINY45-20XU, ATTINY45V-10XUR, ATTINY45-20XUR and ATTINY45V-10XU catalog part numbers (CPN) available in 8L TSSOP (4.4mm) package.

PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of MMT as an additional assembly site for ATTINY45-20XU, ATTINY45V-10XUR, ATTINY45-20XUR and ATTINY45V-10XU catalog part numbers (CPN) available in 8L TSSOP (4.4mm) package.

CN: ES090796-18969
QUAL ID: QTP3000 Rev. A
MP CODE: 354A07D3XC02
Part No.: ATTINY20-SSU
Bonding No.: BDM-001249 rev B
CCB No.: 2831

Lead Frame

Paddle Size: 104x150 mils
Material: A194
DAP Surface Prep: Bare Cu
Process: Etched
Lead Lock: No
Part Number: 10101413
Plating Composition: Matte Tin
Treatment BOT

Bond Wire

Wire: CuPdAu

Die Attach Material

Epoxy: 8390A

Mold Compound

Mold Compound: G600V

Package

Type: 14L SOIC
Package Size: 150 mils

PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MMT-174600762.000	MCSO517440059.000	1706KK9
MMT-174600801.000	MCSO517440059.000	1706MGJ
MMT-174700001.000	MCSO517440059.000	1707MK6

Result: **Pass**

Conclusion:

14L SOIC (.150") assembled by MMT (ALPH) pass reliability test per QCI-39000 which was conducted at MPHL re lab. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020D standard.

PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Precondition	Electrical Test : +85°C System: MT9320 Handler:0202	JESD22-A113	792(0)	792		
	Bake 150°C, 24 hrs System: HERAEUS	JESD22-A113	792	792		
	85°C/85%RH Moisture Soak 168 hrs. System: Climats Excal 5423-HE	IPC/JEDEC J-STD-020D	792	792		
	3x Convection-Reflow 265°C max System: Mancorp CR.5000F	IPC/JEDEC J-STD-020D	792	792		
	Electrical Test : +85°C System: MT9320 Handler:0202		792(0)	0/792	Pass	Good Devices

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Temp Cycle	Stress Condition: (Standard) 65°C to +150°C, 500 Cycles System : VOTSCH VT 7012 S2	JESD22-A104	252(0)	252		Parts had been pre-conditioned at 260°C
	Electrical Test: + 85°C System: MT9320 Handler:0202	JESD22-A104	252(0)	0/252	Pass	
	Bond Strength: Wire Pull (> 2.50 grams) Bond Shear (>15.00 grams)	JESD22-A104	12(0)	0/12	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
UNBIASED-HAST	Stress Condition: (Standard) +130°C/85%RH, 96 hrs. System: HIRAYAMA HASTEST PC-422R8	JESD22-A118	252(0)	252		Parts had been pre-conditioned at 260°C
	Electrical Test : +85°C System: MT9320 Handler:0202	JESD22-A118	252(0)	0/252	Pass	84 units / lot

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
HAST	Stress Condition: (Standard) +130°C/85%RH, 96 hrs. Bias Volt: 5.5 Volts System: HIRAYAMA HASTEST PC-422R8	JESD22-A110	238(0)	238		Parts had been pre-conditioned at 260°C
	Electrical Test : +85°C System: MT9320 Handler:0202	JESD22-A110	238(0)	0/238	Pass	

PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
High Temperature Storage Life	Stress Condition: Bake 175°C, 504 hrs System: HERAEUS	JESD22-A103	45(0)	45		45 units
	Electrical Test: +85°C System: MT9320 Handler:0202	JESD22-A103	45(0)	0/45	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Solderability Temp 215°C	Steam Aging: Temp 93°C, 8Hrs System: SAS-3000	JESD22B-102E	22(0)	22		Performed at MTAI
	Solder Dipping: Solder Temp. 215°C Solder material: SnPb Sn63, Pb37 System: ERSA RA 2200D	JESD22B-102E	22	22		
	Visual Inspection: External Visual Inspection	JESD22B-102E		0/22	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Solderability Temp 245°C	Steam Aging: Temp 93°C, 8Hrs System: SAS-3000	JESD22B-102E	22(0)	22		Performed at MTAI
	Solder Dipping: Solder Temp. 245°C Solder material: Pb Free Sn 95.5Ag3.9Cu0.6 System: ERSA RA 2200D	JESD22B-102E	22	22		
	Visual Inspection: External Visual Inspection	JESD22B-102E		0/22	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Physical Dimensions	Physical Dimension, 30 units from 1 lot	JESD22-B100/B108	30(0) Units	0/30	Pass	Performed at MTAI

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Bond Strength Data Assembly	Wire Pull (>2.50 grams) Bond Shear (>15.00 grams)	M2011.8 / MIL-STD-883	30 (0) Wires / 30 (0) bonds	0/30 / 0/30	Pass / Pass	



Qualification Report Summary

RELIABILITY LABORATORY

PCN #: CBOL-21ZKND337

Date: February 9, 2026

Qualification of MMT as an additional assembly site for ATTINY45-20XU, ATTINY45V-10XUR, ATTINY45-20XUR and ATTINY45V-10XU catalog part numbers (CPN) available in 8L TSSOP (4.4mm) package. This is a Q100 grade 1 qualification.

PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of MMT as an additional assembly site for ATTINY45-20XU, ATTINY45V-10XUR, ATTINY45-20XUR and ATTINY45V-10XU catalog part numbers (CPN) available in 8L TSSOP (4.4mm) package. This is a Q100 qualification.

CN: E000296279
QUAL ID: R2600073 Rev. A
MP CODE: TVAA14C5XB00
Part No.: 23LC1024-E/ST
Bonding No.: BD-002080 Rev. 02
CCB No.: 6798

Lead Frame

Paddle Size: 118 x 87 mils
Material: C7025
DAP Surface Prep: Bare Cu
Process: Stamped
Lead Lock: No
Part Number: 10100848
Plating Composition: Matte tin
Treatment BOT

Bond Wire

Wire: Au wire

Die Attach Material

Epoxy: 8006NS

Mold Compound

Mold Compound: G600V

Package

Type: 8L TSSOP
Package Size: 4.4 mm

PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MMT-264101370.000	U08F924375991.400	2602PSV
MMT-264101570.000	U08F924375991.400	2602UYV
MMT-264101571.000	U08F924375991.400	2602V17

Result: **Pass**

Conclusion:

8L TSSOP (4.4 mm) assembled by MMT pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Precondition Prior Perform Reliability Tests (At MSL Level 1)	Electrical Test: +25°C, 85°C and 125°C System: NEXTEST_PT	JESD22-A113	693(0)	0/693	Pass	Good Devices
	Bake 150°C, 24 hrs. System: CHINEE	JIP/IPC/JEDEC J-STD-020E	693	693		
	85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243			693		
	Electrical Test: +25°C, 85°C and 125°C System: NEXTEST_PT		693(0)	0/693	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Temp Cycle	Stress Condition: -55°C to +150°C, 1000 Cycles System: TABAI ESPEC TSA-70H	JESD22-A104	231		Pass	Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C, 85°C and 125°C System: NEXTEST_P				Pass	77 units / lot
	Bond Strength: Wire Pull (>2.50 grams)					

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
UNBIASED-HAST	Stress Condition: +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22-A118	231			Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: NEXTEST_PT		231(0)	0/231	Pass	77 units / lot

PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
HAST	Stress Condition: +130°C/85%RH, 96 hrs. Bias Volt: 5.5 Volts System: HAST 6000X	JESD22-A110	231			Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C, 85°C and 125°C System: NEXTEST_PT		231(0)	0/231	Pass	77 units / lot

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
High Temperature Storage Life	Stress Condition: Bake 175°C, 500 hrs. System: CHINEE, TPS Bake Oven	JESD22-A103	45	45	Pass	45 units
	Electrical Test: +25°C, 85°C and 125°C System: NEXTEST_PT					

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Solderability Temp 245°C	Steam Aging: Temp 93°C, 8Hrs System: SAS-3000	J-STD-002	22(0)	22	Pass	
	Solder Dipping: Solder Temp.245°C Solder material: Pb Free Sn 95.5Ag3.9Cu0.6 System: ERSA RA 2200D			22		
	Visual Inspection: External Visual Inspection			0/22	Pass	

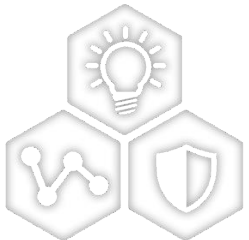
Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Physical Dimensions	Physical Dimension 10 units / 1 lot	JESD22-B100/B108	30(0) Units	0/30	Pass	Physical Dimension

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Bond Strength Data Assembly	Wire Pull (>2.50 grams)	Mil. Std. 883-2011	30(0) Wires	0/30	Pass	
	Bond Shear (>15.00 grams)	CDF-AEC-Q100-001	30(0) Bonds	0/30	Pass	

CCB 8394
Pre and Post Change Summary
PCN #: CBOL-21ZKND337



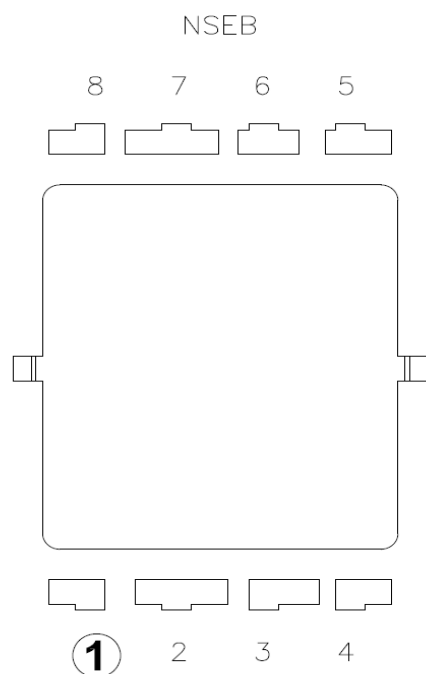
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Lead Frame Comparison

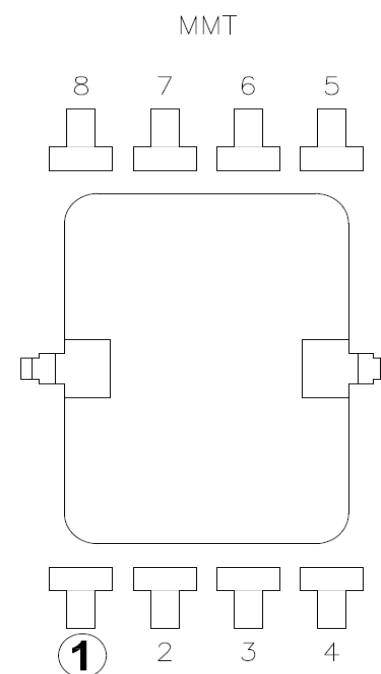
NSEB



Note: Not to scale

DAP Surface Prep	Spot Plating
Lead-Frame Paddle Size	118x104 mils

MMT



Note: Not to scale

DAP Surface Prep	Bare Cu
Lead-Frame Paddle Size	118x87 mils